

ABSTRACT

The present invention comprises: a collet (18) that suctions a semiconductor die (15); a sucking mechanism (100) that sucks air from a front surface (18a) of the collet; a
5 flow rate sensor (106) that detects the sucked air flow rate of the sucking mechanism; a stage (20) that includes a suction surface (22) suctioning a back surface (12b) of a dicing sheet (12); an aperture pressure switching mechanism (80) that, at the time of pickup, switches the aperture pressure of an aperture (23) provided to the suction surface of the stage, between a first pressure that is close to a vacuum and a second pressure that is close
10 to atmospheric pressure; and a control unit (150), wherein the control unit acquires the variation over time of the sucked air flow rate detected by the flow rate sensor during pickup of a specific semiconductor die, calculates, from said variation over time, the ease of release of the semiconductor die from the dicing sheet, and on the basis of said ease of release, modifies the number of switches during pickup of subsequent semiconductor dice.
15 Thus, an appropriate balance can be achieved between accelerating pickup and suppressing damage to semiconductor dice during pickup.

FIGURE 1